



128Kx16 SRAM/512Kx16 FLASH MODULE

FEATURES

- Access Times of 35ns (SRAM) and 90ns (FLASH)
- Packaging
 - 66 pin, PGA Type, 1.075" square HIP, Hermetic Ceramic HIP (Package 400)
 - 68 lead, Hermetic CQFP (G2U), 22.4mm (0.880") square (Package 510) 3.56mm (0.140") height. Designed to fit JEDEC 68 lead 0.990" CQFJ footprint (FIGURE 2)
- 128Kx16 SRAM
- 512Kx16 5V FLASH
- Organized as 128Kx16 of SRAM and 512Kx16 of Flash Memory with separate Data Buses
- Both blocks of memory are User Configurable as 256Kx8
- Low Power CMOS
- Commercial, Industrial and Military Temperature Ranges
- TTL Compatible Inputs and Outputs

- Built-in Decoupling Caps and Multiple Ground Pins for Low Noise Operation
- Weight:
 - WSF2816-39G2UX - 8 grams typical
 - WSF2816-39H1X - 13 grams typical

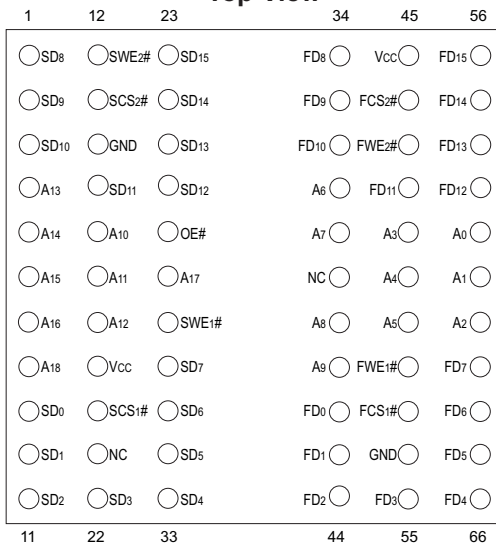
FLASH MEMORY FEATURES

- 100,000 Erase/Program Cycles
- Sector Architecture
 - 8 equal size sectors of 64K bytes each
 - Any combination of sectors can be concurrently erased. Also supports full chip erase
- 5 Volt Programming; 5V ± 10% Supply
- Embedded Erase and Program Algorithms
- Hardware Write Protection

Note: For programming information refer to Flash Programming 4M5 Application Note.

FIGURE1 – PIN CONFIGURATION FOR WSF2816-39H1X

Top View



Pin Description

FD0-15	Flash Data Inputs/Outputs
SD0-15	SRAM Data Inputs/Outputs
A0-18	Address Inputs
SWE1-2#	SRAM Write Enable
SCS1-2#	SRAM Chip Selects
OE#	Output Enable
Vcc	Power Supply
GND	Ground
NC	Not Connected
FWE1-2#	Flash Write Enable
FCS1-2#	Flash Chip Select

Block Diagram

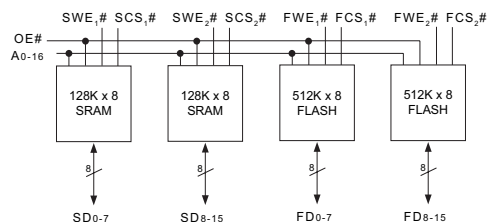
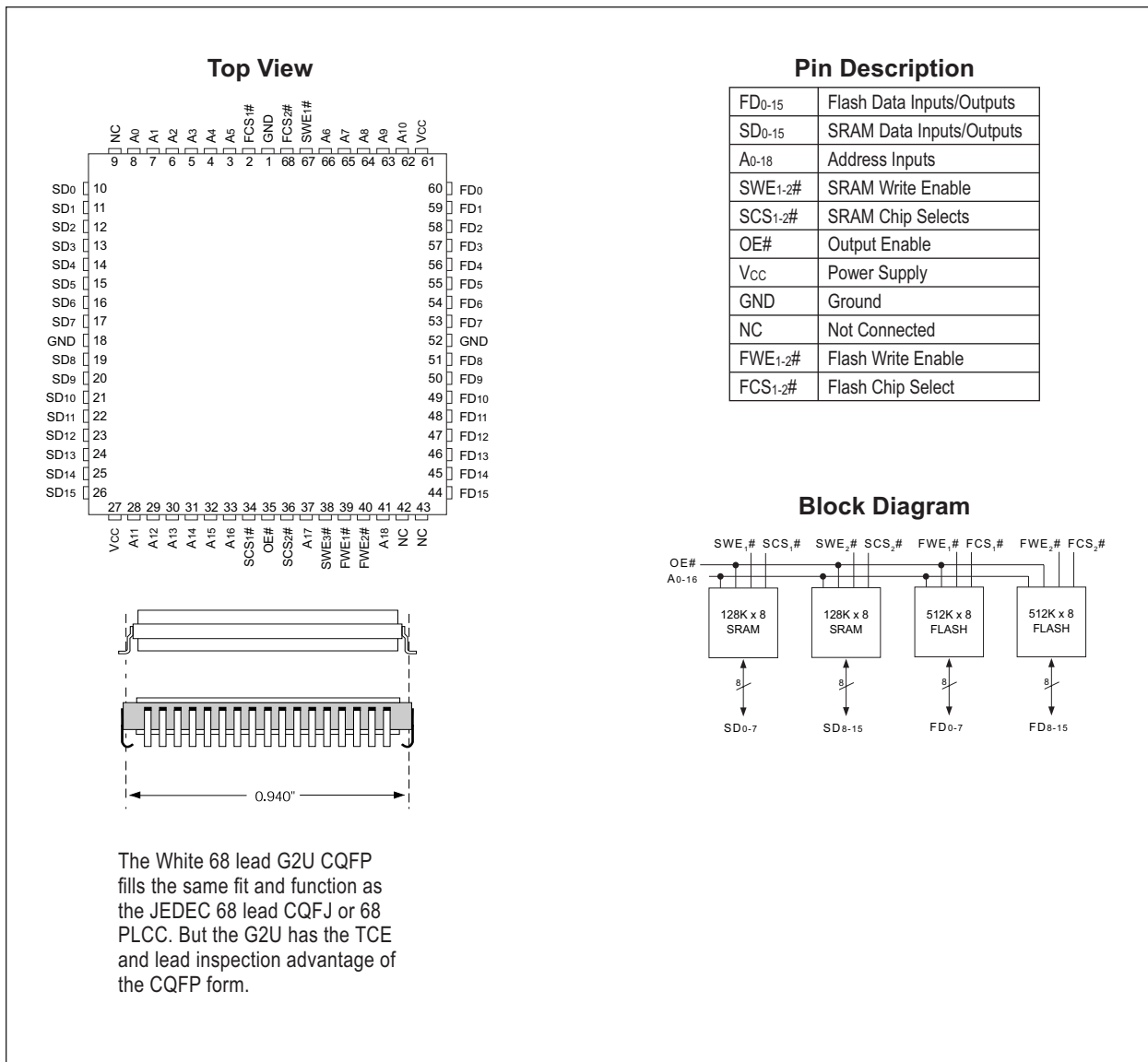




FIGURE 2 – PIN CONFIGURATION FOR WSF2816-39G2UX





ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Operating Temperature	T _A	-55	+125	°C
Storage Temperature	T _{STG}	-65	+150	°C
Signal Voltage Relative to GND	V _G	-0.5	7.0	V
Junction Temperature	T _J		150	°C
Supply Voltage	V _{CC}	-0.5	7.0	V

Parameter	Symbol	Min	Max	Unit
Flash Data Retention			20 years	
Flash Endurance (write/erase cycles)			100,000	

NOTES: 1. Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

SRAM TRUTH TABLE

SCS#	OE#	SWE#	Mode	Data I/O	Power
H	X	X	Standby	High Z	Standby
L	L	H	Read	Data Out	Active
L	H	H	Read	High Z	Active
L	X	L	Write	Data In	Active

CAPACITANCE

T_A = +25°C

Test	Symbol	Condition	Max	Unit
OE# Capacitance	C _{OE}	V _{IN} = 0V, f = 1.0MHz	50	pF
WE# Capacitance	C _{WE}	V _{IN} = 0V, f = 1.0MHz	20	pF
CS# Capacitance	C _{CS}	V _{IN} = 0V, f = 1.0MHz	20	pF
Data I/O Capacitance	C _{I/O}	V _{IN} = 0V, f = 1.0MHz	20	pF
Address Line Capacitance	C _{AD}	V _{IN} = 0V, f = 1.0MHz	50	pF

This parameter is guaranteed by design but not tested.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V _{CC}	4.5	5.5	V
Input High Voltage	V _{IH}	2.2	V _{CC} + 0.3	V
Input Low Voltage	V _{IL}	-0.5	+0.8	V

DC CHARACTERISTICS

V_{CC} = 5.0V, V_{SS} = 0V, -55°C ≤ T_A ≤ +125°C

Parameter	Symbol	Conditions	Min	Max	Unit
Input Leakage Current	I _{LI}	V _{CC} = 5.5, V _{IN} = GND to V _{CC}		10	μA
Output Leakage Current	I _{LO}	SCS# = V _{IH} , OE# = V _{IH} , V _{OUT} = GND to V _{CC}		10	μA
SRAM Operating Supply Current x 16 Mode	I _{CCx16}	SCS# = V _{IL} , OE# = FCS# = V _{IH} , f = 5MHz, V _{CC} = 5.5		325	mA
Standby Current	I _{SB}	FCS# = SCS# = V _{IH} , OE# = V _{IH} , f = 5MHz, V _{CC} = 5.5		20	mA
SRAM Output Low Voltage	V _{OL}	I _{OL} = 8.0mA, V _{CC} = 4.5		0.4	V
SRAM Output High Voltage	V _{OH}	I _{OH} = -4.0mA, V _{CC} = 4.5	2.4		V
Flash V _{CC} Active Current for Read (1)	I _{CC1}	FCS# = V _{IL} , OE# = SCS# = V _{IH}		120	mA
Flash V _{CC} Active Current for Program or Erase (2)	I _{CC2}	FCS# = V _{IL} , OE# = SCS# = V _{IH}		140	mA
Flash Output Low Voltage	V _{OL}	I _{OL} = 8.0mA, V _{CC} = 4.5		0.45	V
Flash Output High Voltage	V _{OH1}	I _{OH} = -2.5 mA, V _{CC} = 4.5	0.85 x V _{CC}		V
Flash Output High Voltage	V _{OH2}	I _{OH} = -100 μA, V _{CC} = 4.5	V _{CC} - 0.4		V
Flash Low V _{CC} Lock Out Voltage	V _{LKO}		3.2		V

NOTES:

- The I_{CC} current listed includes both the DC operating current and the frequency dependent component (@ 5 MHz).
The frequency component typically is less than 2mA/MHz, with OE# at V_{IH}.
- I_{CC} active while Embedded Algorithm (program or erase) is in progress.
- DC test conditions: V_{IL} = 0.3V, V_{IH} = V_{CC} - 0.3V



SRAM AC CHARACTERISTICS

$V_{CC} = 5.0V, -55^{\circ}C \leq T_A \leq +125^{\circ}C$

Parameter Read Cycle	Symbol	-35		Unit
		Min	Max	
Read Cycle Time	t_{RC}	35		ns
Address Access Time	t_{AA}		35	ns
Output Hold from Address Change	t_{OH}	0		ns
Chip Select Access Time	t_{ACS}		35	ns
Output Enable to Output Valid	t_{OE}		20	ns
Chip Select to Output in Low Z	t_{CLZ}^1	3		ns
Output Enable to Output in Low Z	t_{OLZ}^1	0		ns
Chip Disable to Output in High Z	t_{CHZ}^1		20	ns
Output Disable to Output in High Z	t_{OHZ}^1		20	ns

1. This parameter is guaranteed by design but not tested.

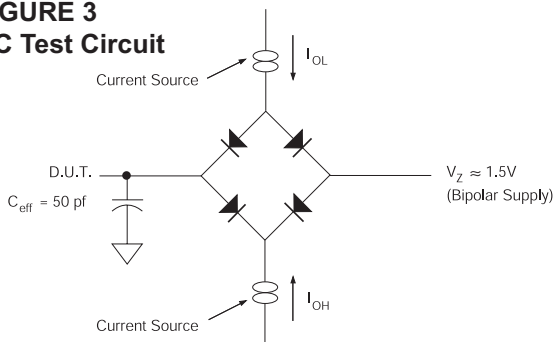
SRAM AC CHARACTERISTICS

$V_{CC} = 5.0V, -55^{\circ}C \leq T_A \leq +125^{\circ}C$

Parameter Write Cycle	Symbol	-35		Unit
		Min	Max	
Write Cycle Time	t_{WC}	35		ns
Chip Select to End of Write	t_{CW}	25		ns
Address Valid to End of Write	t_{AW}	25		ns
Data Valid to End of Write	t_{DW}	20		ns
Write Pulse Width	t_{WP}	25		ns
Address Setup Time	t_{AS}	0		ns
Address Hold Time	t_{AH}	0		ns
Output Active from End of Write	t_{OW1}	4		ns
Write Enable to Output in High Z	t_{WHZ1}		20	ns
Data Hold from Write Time	t_{DH}	0		ns

1. This parameter is guaranteed by design but not tested.

**FIGURE 3
AC Test Circuit**



AC TEST CONDITIONS

Parameter	Typ	Unit
Input Pulse Levels	$V_{IL} = 0, V_{IH} = 3.0$	V
Input Rise and Fall	5	ns
Input and Output Reference Level	1.5	V
Output Timing Reference Level	1.5	V

Notes: V_Z is programmable from -2V to +7V.
 I_{OL} & I_{OH} programmable from 0 to 16mA.
 Tester Impedance $Z_0 = 75\Omega$.
 V_Z is typically the midpoint of V_{OH} and V_{OL} .
 I_{OL} & I_{OH} are adjusted to simulate a typical resistive load circuit.
 ATE tester includes jig capacitance.



FIGURE 4 – SRAM TIMING WAVEFORM — READ CYCLE

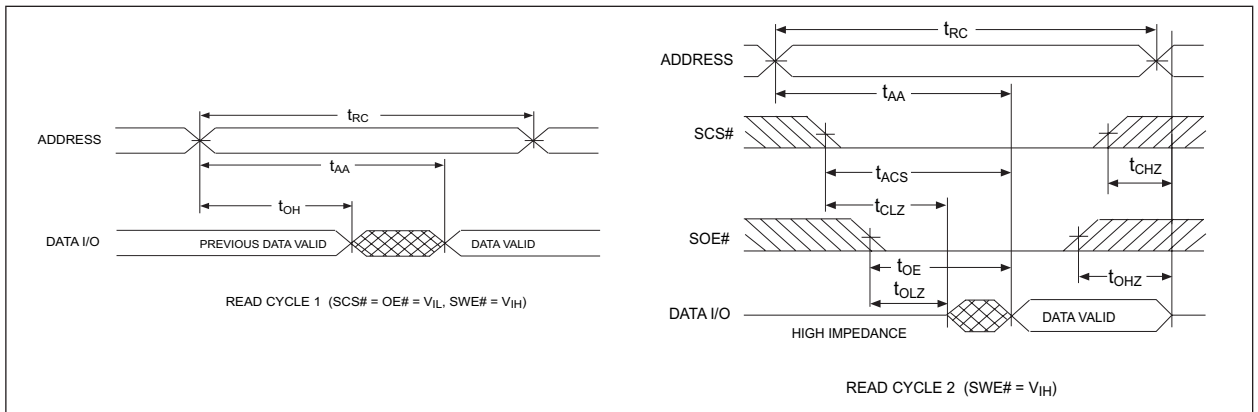


FIGURE 5 – SRAM WRITE CYCLE — SWE# CONTROLLED

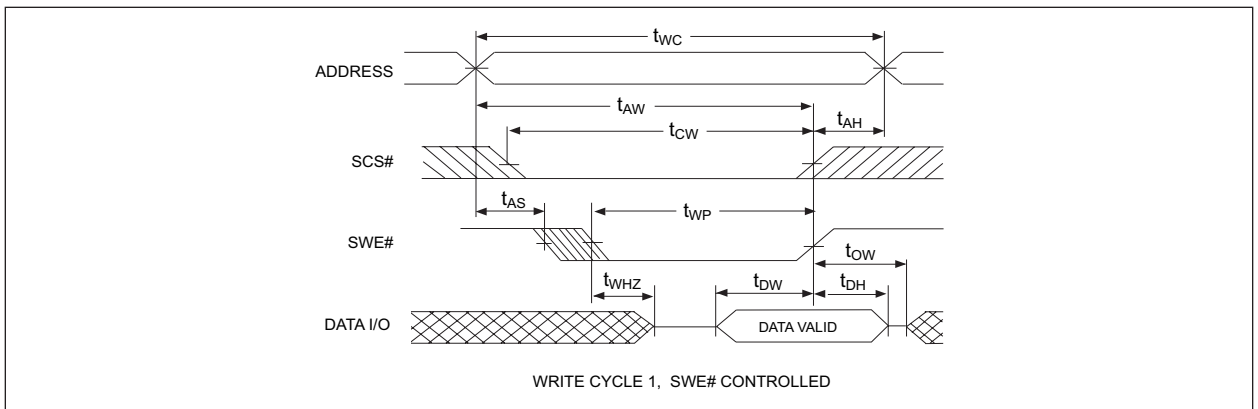
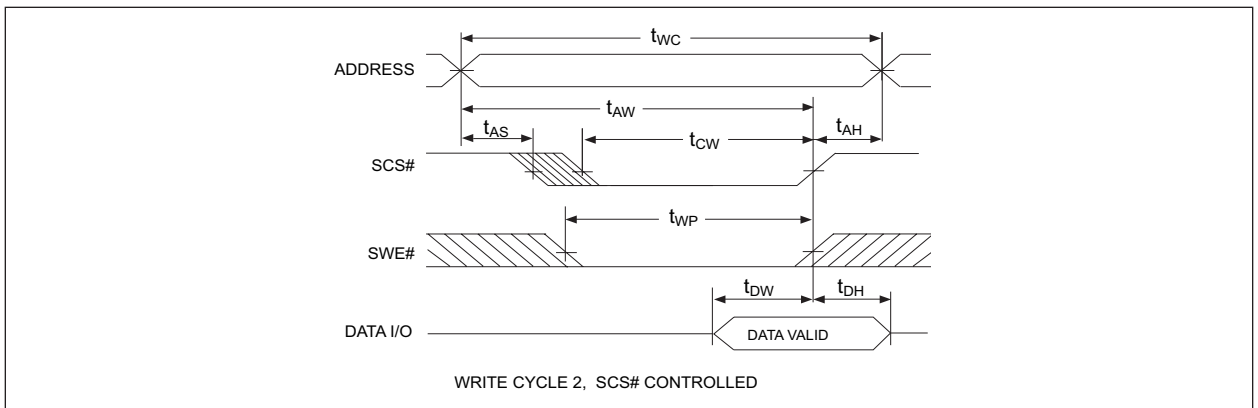


FIGURE 6 – SRAM WRITE CYCLE — SCS# CONTROLLED





FLASH AC CHARACTERISTICS – WRITE/ERASE/PROGRAM OPERATIONS, FWE# CONTROLLED

$V_{CC} = 5.0V, -55^{\circ}C \leq T_A \leq +125^{\circ}C$

Parameter	Symbol		-90		Unit
			Min	Max	
Write Cycle Time	t _{AVAV}	t _{WC}	90		ns
Chip Select Setup Time	t _{ELWL}	t _{CS}	0		ns
Write Enable Pulse Width	t _{WLWH}	t _{WP}	45		ns
Address Setup Time	t _{AVWL}	t _{AS}	0		ns
Data Setup Time	t _{DVWH}	t _{DS}	45		ns
Data Hold Time	t _{WHDX}	t _{DH}	0		ns
Address Hold Time	t _{WLAX}	t _{AH}	45		ns
Chip Select Hold Time	t _{WHEH}	t _{CH}	0		ns
Write Enable Pulse Width High	t _{WHWL}	t _{WPH}	20		ns
Duration of Byte Programming Operation (1)	t _{WHWH1}			300	μs
Sector Erase Time (2)	t _{WHWH2}			15	sec
Read Recovery Time Before Write	t _{GHWL}		0		μs
V _{CC} Set-up Time		t _{VCS}	50		μs
Chip Programming Time				11	sec
Output Enable Setup Time		t _{OES}	0		ns
Output Enable Hold Time (1)		t _{OEH}	10		ns
Chip Erase Time				64	sec

NOTES:

1. Typical value for t_{WHWH1} is 7μs.
2. Typical value for t_{WHWH1} is 1sec.
3. Typical value for Chip Erase Time is 8sec.
4. For Toggle and Data# Polling.

FLASH AC CHARACTERISTICS – READ ONLY OPERATIONS

$V_{CC} = 5.0V, -55^{\circ}C \leq T_A \leq +125^{\circ}C$

Parameter	Symbol		-90		Unit
			Min	Max	
Read Cycle Time	t _{AVAV}	t _{RC}	90		ns
Address Access Time	t _{AVQV}	t _{ACC}		90	ns
Chip Select Access Time	t _{ELQV}	t _{CE}		90	ns
OE# to Output Valid	t _{GLQV}	t _{OE}		35	ns
Chip Select to Output High Z (1)	t _{EHQZ}	t _{DF}		20	ns
OE# High to Output High Z (1)	t _{GHQZ}	t _{DF}		20	ns
Output Hold from Address, CS# or OE# Change, whichever is first	t _{AXQX}	t _{OH}	0		ns

1. Guaranteed by design, not tested.



FLASH AC CHARACTERISTICS – WRITE/ERASE/PROGRAM OPERATIONS, FCS# CONTROLLED

V_{CC} = 5.0V, -55°C ≤ T_A ≤ +125°C

Parameter	Symbol		-90		Unit
			Min	Max	
Write Cycle Time	t _{AVAV}	t _{WC}	90		ns
FWE# Setup Time	t _{WLEL}	t _{WS}	0		ns
FCS# Pulse Width	t _{ELEH}	t _{CP}	45		ns
Address Setup Time	t _{AVEL}	t _{AS}	0		ns
Data Setup Time	t _{DVEH}	t _{DS}	45		ns
Data Hold Time	t _{EHDX}	t _{DH}	0		ns
Address Hold Time	t _{ELAX}	t _{AH}	45		ns
FWE# Hold From FWE# High	t _{EHWH}	t _{WH}	0		ns
FCS# Pulse Width High	t _{EHEL}	t _{CPH}	20		ns
Duration Of Byte Programming Operation (1)	t _{WHWH1}			300	μs
Duration Of Erase Operation (2)	t _{WHWH2}			15	sec
Read Recovery Before Write	t _{GHEL}		0		ns
Chip Programming Time				11	sec
Chip Erase Time (3)				64	sec

NOTES:

1. Typical value for t_{WHWH1} is 7μs.
2. Typical value for t_{WHWH1} is 1sec.
3. Typical value for Chip Erase Time is 8sec.



FIGURE 7 – AC WAVEFORMS FOR FLASH MEMORY READ OPERATIONS

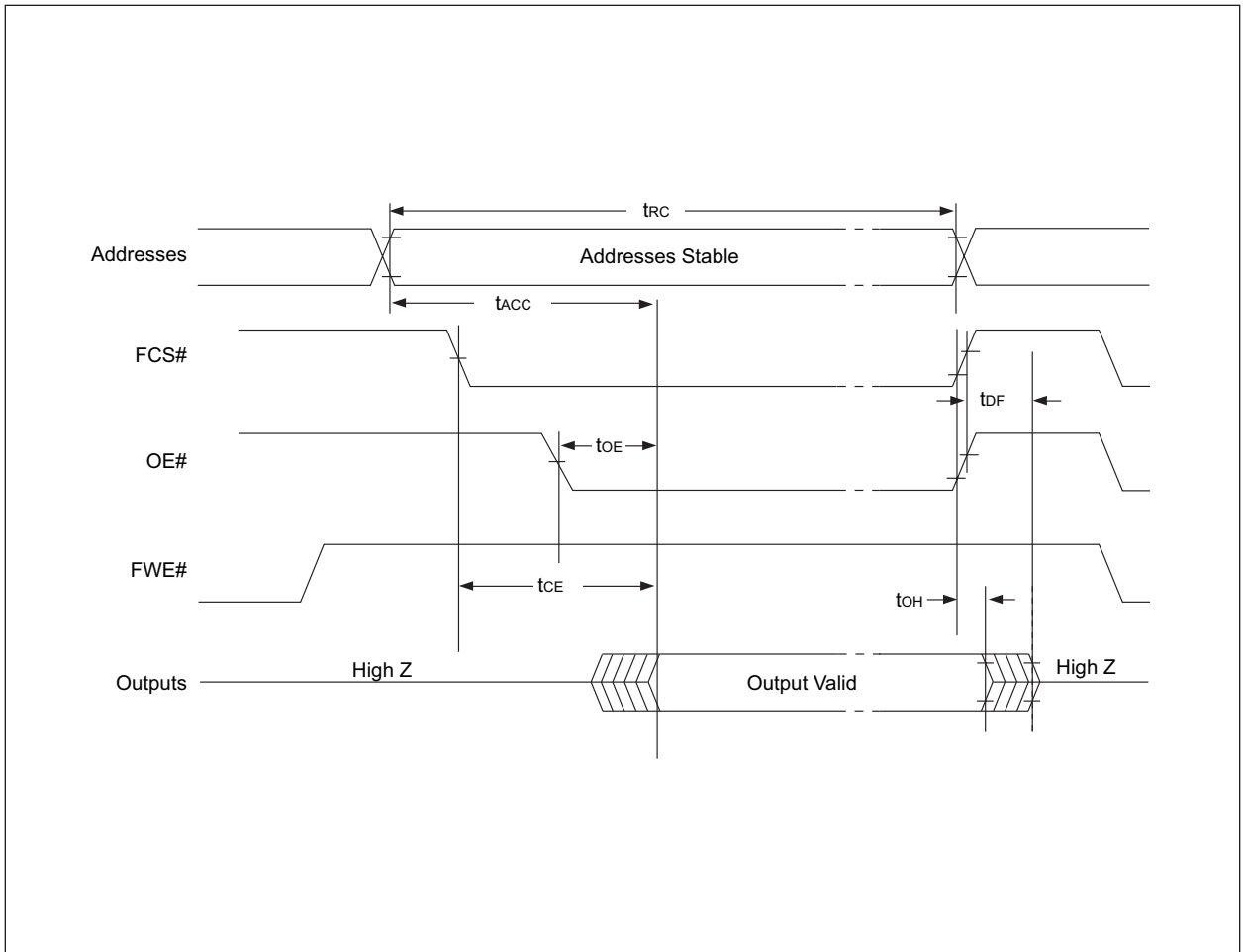
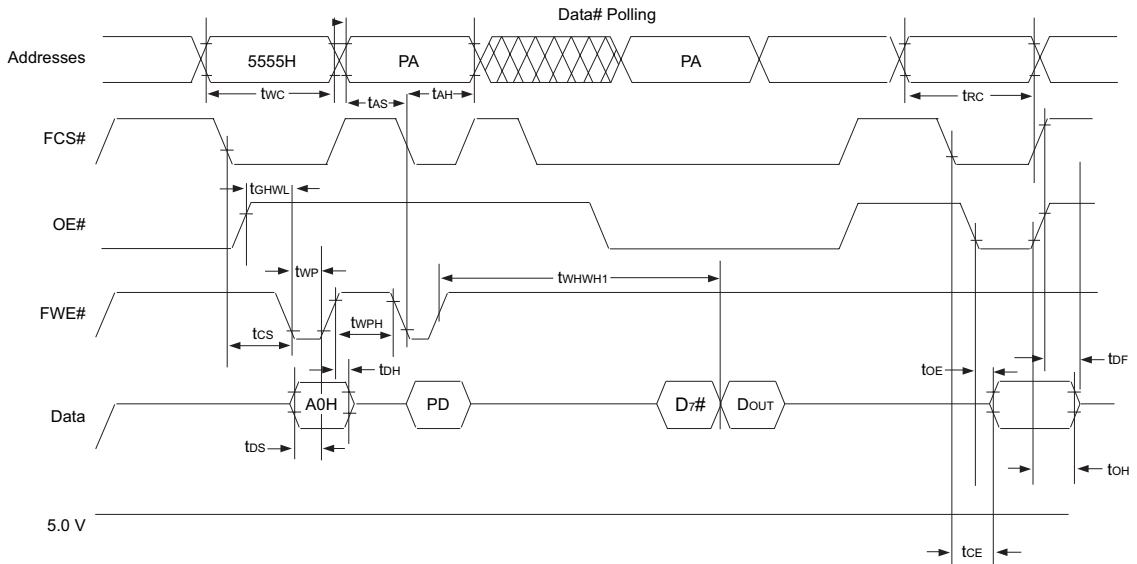




FIGURE 8 – WRITE/ERASE/PROGRAM OPERATION, FLASH MEMORY FWE# CONTROLLED



- NOTES:
1. PA is the address of the memory location to be programmed.
 2. PD is the data to be programmed at byte address.
 3. D7# is the output of the complement of the data written to the device.
 4. DOUT is the output of the data written to the device.
 5. Figure indicates last two bus cycles of four bus cycle sequence.



FIGURE 9 – AC WAVEFORMS CHIP/SECTOR ERASE OPERATIONS FOR FLASH MEMORY

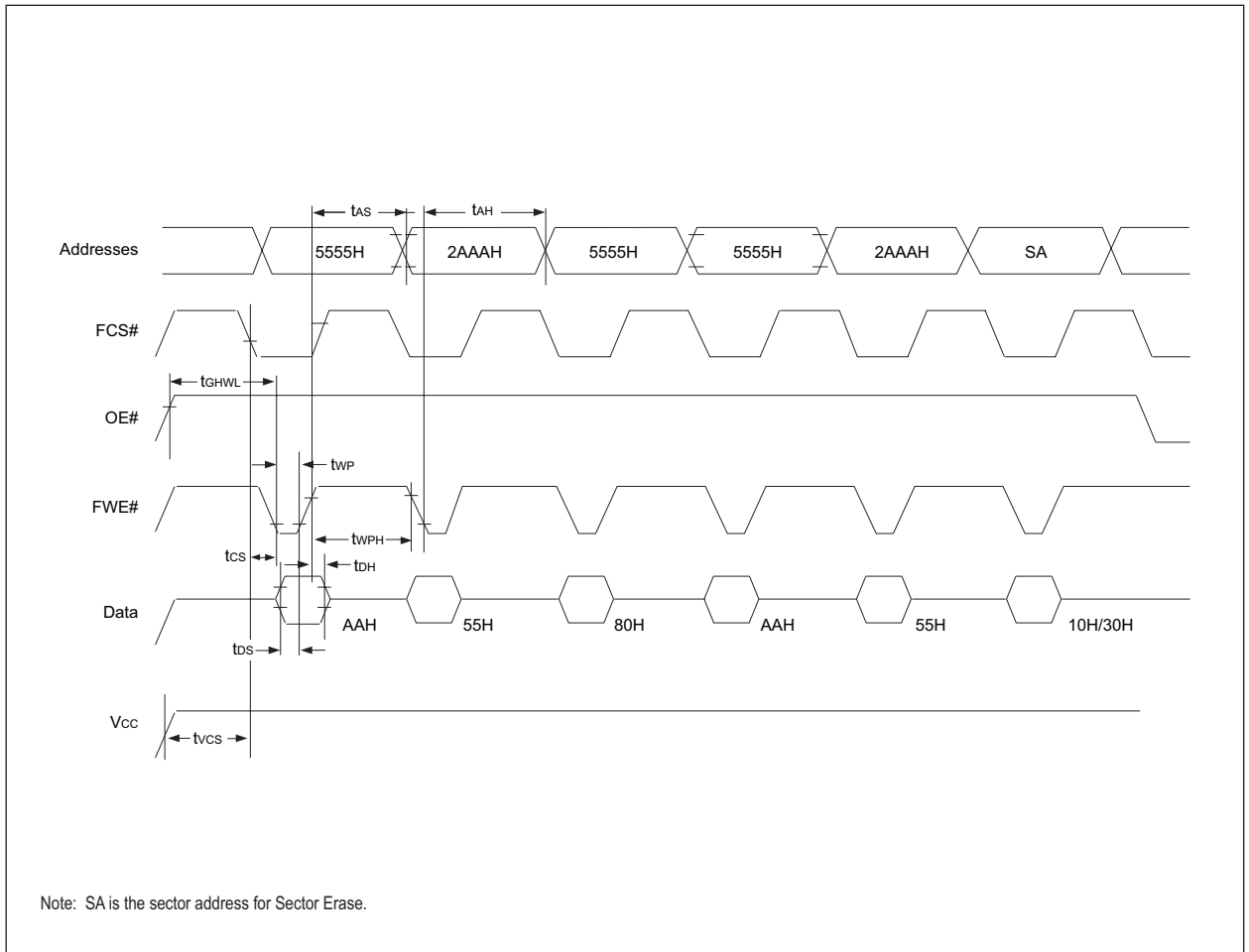




FIGURE 10 – AC WAVEFORMS FOR DATA# POLLING DURING EMBEDDED ALGORITHM OPERATIONS FOR FLASH MEMORY

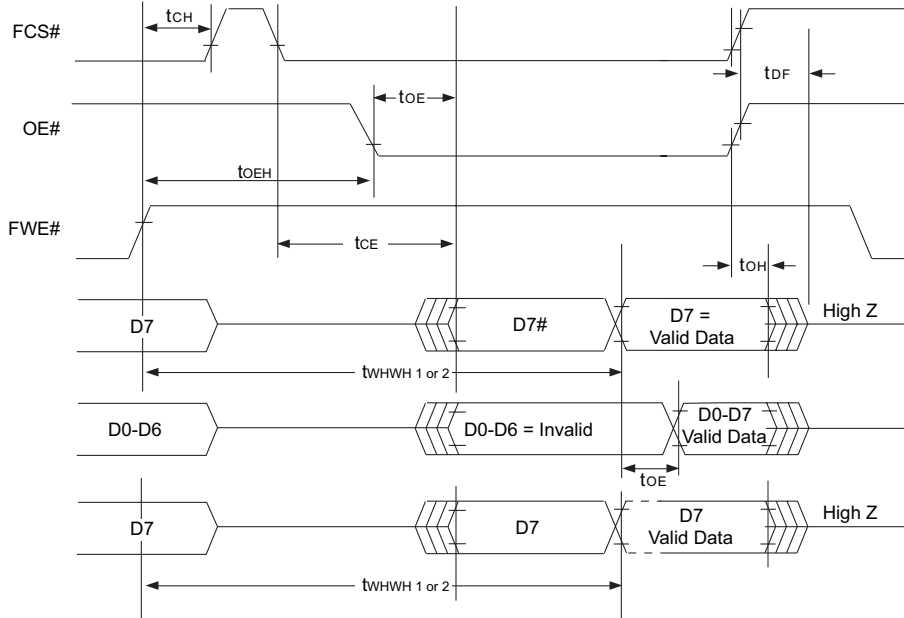
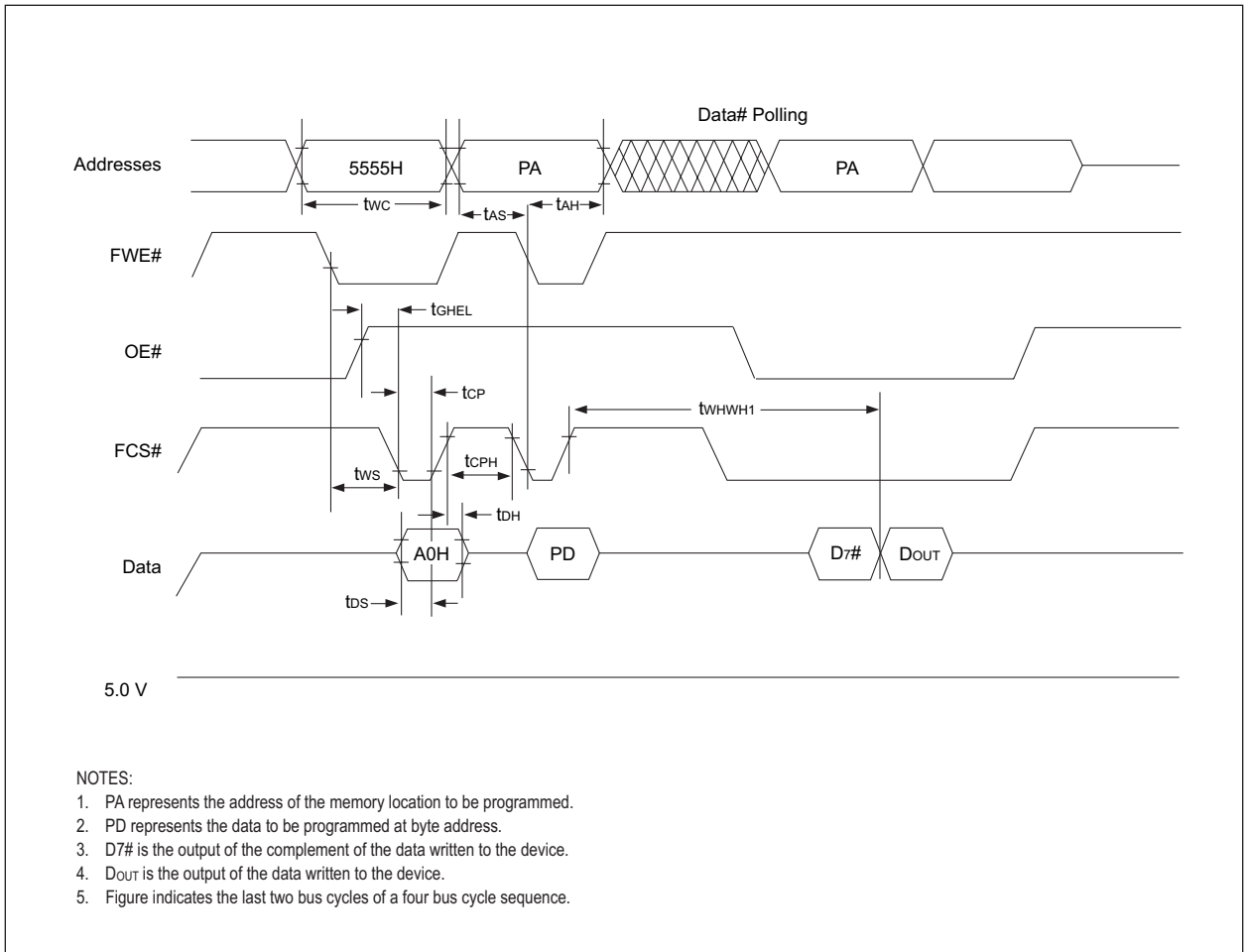


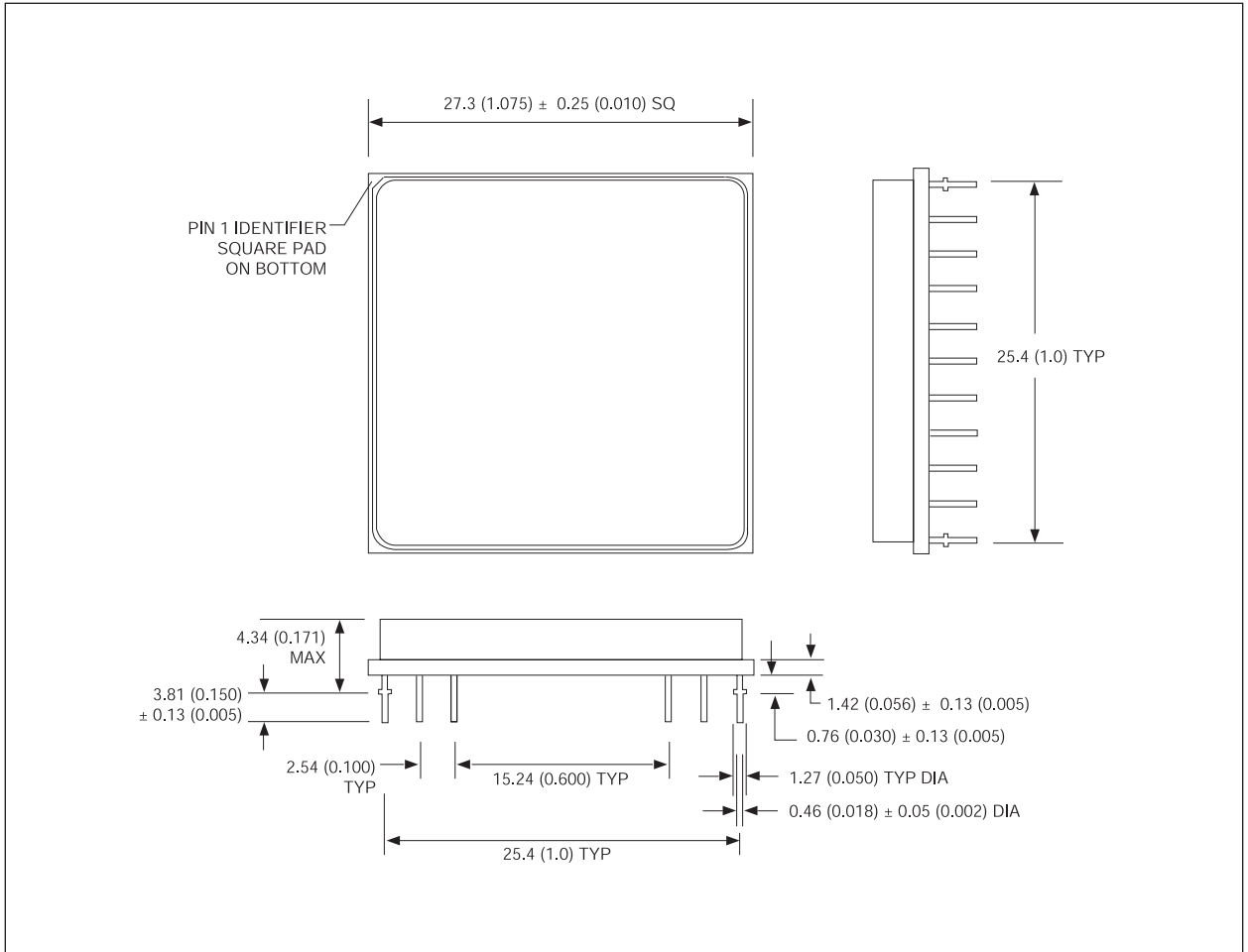


FIGURE 11 – WRITE/ERASE/PROGRAM OPERATION FOR FLASH MEMORY, CS# CONTROLLED





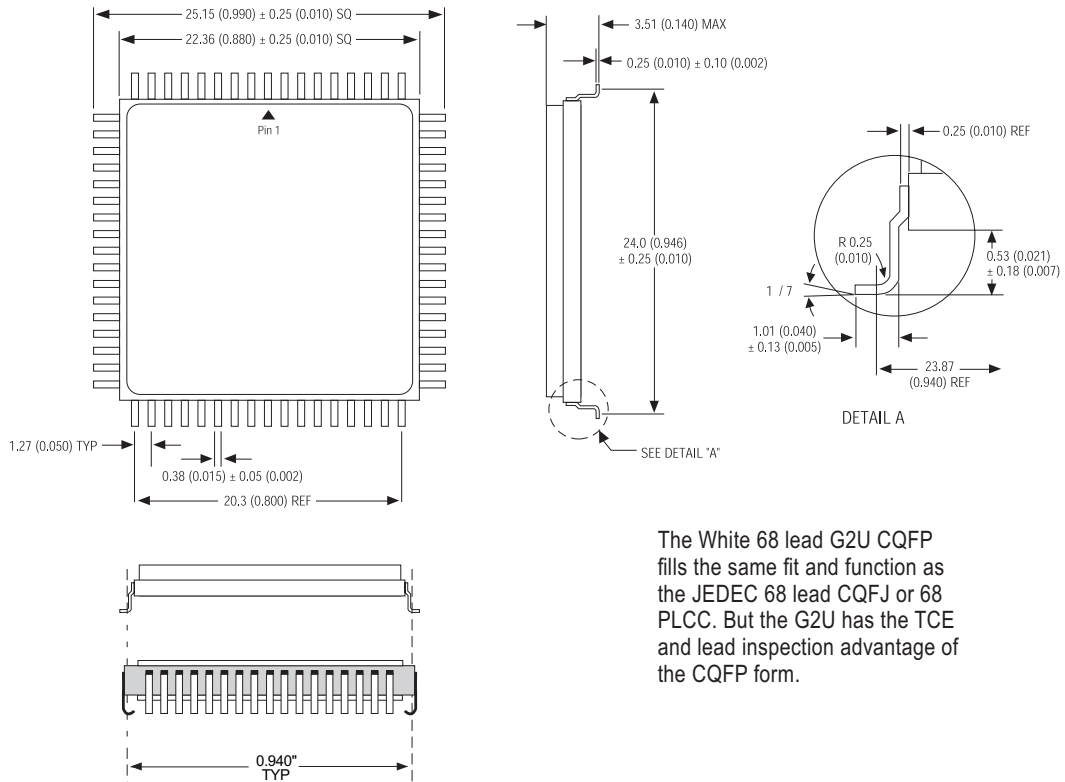
PACKAGE 400: 66 PIN, PGA TYPE, CERAMIC HEX-IN-LINE PACKAGE, HIP (H1)



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES



PACKAGE 510: 68 LEAD, CERAMIC QUAD FLAT PACK, CQFP (G2U)



The White 68 lead G2U CQFP fills the same fit and function as the JEDEC 68 lead CQFJ or 68 PLCC. But the G2U has the TCE and lead inspection advantage of the CQFP form.

ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES



ORDERING INFORMATION

W S F 2816 - 39 X X X

LEAD FINISH:

Blank = Gold plated leads
A = Solder dip leads

DEVICE GRADE:

M = Military Screened -55°C to +125°C
I = Industrial -40°C to +85°C
C = Commercial 0°C to +70°C

PACKAGE TYPE:

H1 = 1.075" sq. Ceramic Hex In-line Package, HIP (Package 400)
G2U = 22.4mm Ceramic Quad Flat Pack, CQFP (Package 510)

ACCESS TIME (ns)

39 = 35ns SRAM and 90ns FLASH

2Mbit of SRAM and 8Mbit of Flash

Organization: 128K x 16 SRAM and
512K x 16 Flash

Flash

SRAM

WHITE ELECTRONIC DESIGNS CORP.